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Responsible committee: EPL/501 Electronic Assembly Technology

Interested committees:

Title: Draft BS EN IEC 63215-5 Endurance test methods for die attach materials. Part 5: Temperature cycling test methods for die attach materials (system soldering interconnection) applied to module type power electronic devices.

Please notify the secretary if you are aware of any keywords that might assist in classifying or identifying the standard or if the content of this standard

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- ii) affects other national standard(s)
- iii) requires additional national guidance or information

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Introduction

This draft standard is based on national and international discussions. Your comments on this draft are invited and will assist in the preparation of the consequent standard.

For international standards, comments will be reviewed by the relevant UK national committee before sending the consensus UK vote and comments to the international committee, which will then decide appropriate action. If the international standard is approved, it is usual for the text to be published as a British Standard.

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UK Vote

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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx
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1	2	(3)	4	5	(6)	7
MB	Clause No./ Subclause No./Annex (e.g. 3.1)	Paragraph/Figure/ Table/Note	Type of comment	Commend (justification for change) by the MB	Proposed change by the MB	Secretariat observations on each comment submitted
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	



91/1770/CD

COMMITTEE DRAFT (CD)

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IEC 63215-5 ED1

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2021-12-03

CLOSING DATE FOR COMMENTS:

2022-02-25

SUPERSEDES DOCUMENTS:

91/1707/NP, 91/1735/RVN

IEC TC 91 : ELECTRONICS ASSEMBLY TECHNOLOGY

SECRETARIAT:

Japan

SECRETARY:

Mr Masahide Okamoto

OF INTEREST TO THE FOLLOWING COMMITTEES:

TC 22,TC 47,SC 47D,SC 47E

PROPOSED HORIZONTAL STANDARD:



Other TC/SCs are requested to indicate their interest, if any, in this CD to the secretary.

FUNCTIONS CONCERNED:

☐ EMC

☐ ENVIRONMENT

☐ QUALITY ASSURANCE

☐ SAFETY

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Recipients of this document are invited to submit, with their comments, notification of any relevant patent rights of which they are aware and to provide supporting documentation.

TITLE:

Endurance test methods for die attach materials – Part 5: Temperature cycling test methods for die attach materials (system soldering interconnection) applied to module type power electronic devices

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CONTENTS

FOREWORD.....	3
1 Scope.....	5
2 Normative references	5
3 Terms, definitions and abbreviated terms	6
3.1 Terms and definitions.....	6
3.2 Abbreviated terms.....	6
4 General	6
5 Test apparatus	7
5.1 Temperature cycling chamber	7
5.2 Ultrasonic flaw inspection equipment	7
6 Specimen	7
6.1 General.....	7
6.2 Preparation of specimen	7
7 Evaluation test	7
7.1 Test method.....	7
7.1.1 General	7
7.1.2 Temperature cycling test	7
7.1.3 Test conditions.....	8
7.1.4 End of test criteria.....	9
7.2 Inspection and measurement	9
7.2.1 Visual inspection.....	9
7.2.2 Ultrasonic flaw inspection.....	9
7.3 Test procedure.....	9
7.3.1 Test preparation.....	9
7.3.2 Preconditioning	9
7.3.3 Initial measurement.....	9
7.3.4 Test.....	9
7.3.5 Intermediate measurement.....	9
7.3.6 Post-test treatment.....	9
7.3.7 Final judgment	10
8 Items to be specified in the product specification.....	10
Annex A (informative) Validity of temperature cycling test conditions	11
A.1 Specimen	11
A.2 Result of temperature cycling test.....	12
A.2.1 Ultrasonic flaw inspection.....	12
A.2.2 Crack area ratio	12
Annex B (informative) Failure cycle and reliability performance index	14
B.1 Failure cycle and reliability performance index.....	14

INTERNATIONAL ELECTROTECHNICAL COMMISSION

ENDURANCE TEST METHODS FOR DIE ATTACH MATERIALS –

**Part 5: Temperature cycling test methods
for die attach materials (system soldering interconnection) applied to
module type power electronic devices**

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International Standard IEC 63215-5 has been prepared by IEC technical committee TC91.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
XX/XX/FDIS	XX/XX/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 5.